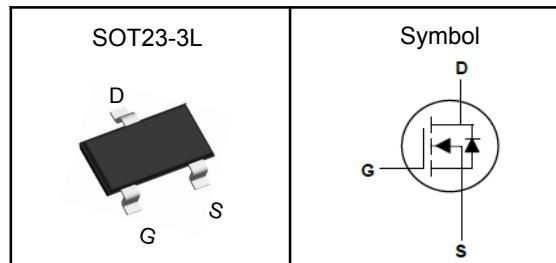


N-Channel Enhancement Mode MOSFET

Features

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant
- 100% UIS and Rg Tested

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

V_{DSS}	150	V
$R_{DS(ON)-Typ}$	260	$m\Omega$
I_D	2	A

Absolute Maximum Ratings ($T_A=25^\circ C$, Unless Otherwise Noted)

Symbol	Parameter	N-Channel	Unit
V_{DSS}	Drain-Source Voltage	150	V
V_{GSS}	Gate-Source Voltage	± 20	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
$I_{DM}^{①}$	Pulse Drain Current Tested	6	A
I_D	Continuous Drain Current	2	A
P_D	Maximum Power Dissipation	2	W

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ₁ (Max)	62.5	$^\circ C/W$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.



N-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	150	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=150\text{V}$, $V_{\text{GS}}=0\text{V}$	---	---	1	μA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$	1.5	---	2.5	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$R_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=10\text{V}$, $I_D=1.5\text{A}$	---	260	300	$\text{m}\Omega$
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=25\text{V}$, Freq.=1MHz	---	235	---	pF
C_{oss}	Output Capacitance		---	36	---	
C_{rss}	Reverse Transfer Capacitance		---	20	---	
$T_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=75\text{V}$, $I_D=1\text{A}$, $R_L=75\Omega$, $V_{\text{GS}}=10\text{V}$, $R_G=6\Omega$	---	8	---	nS
T_r	Turn-on Rise Time		---	10	---	
$T_{\text{d(off)}}$	Turn-off Delay Time		---	20	---	
T_f	Turn-off Fall Time		---	15	---	
Q_g	Total Gate Charge	$V_{\text{DS}}=75\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=1.5\text{A}$	---	8	---	nC
Q_{gs}	Gate-Source Charge		---	1.4	---	
Q_{gd}	Gate-Drain Charge		---	2.1	---	
Source-Drain Characteristics ($T_J=25^\circ\text{C}$)						
V_{SD}	Diode Forward Voltage ₂	$V_{\text{GS}}=0\text{V}$, $I_S=2\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V

Note ④ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

N-Channel Enhancement Mode MOSFET

Typical Characteristics

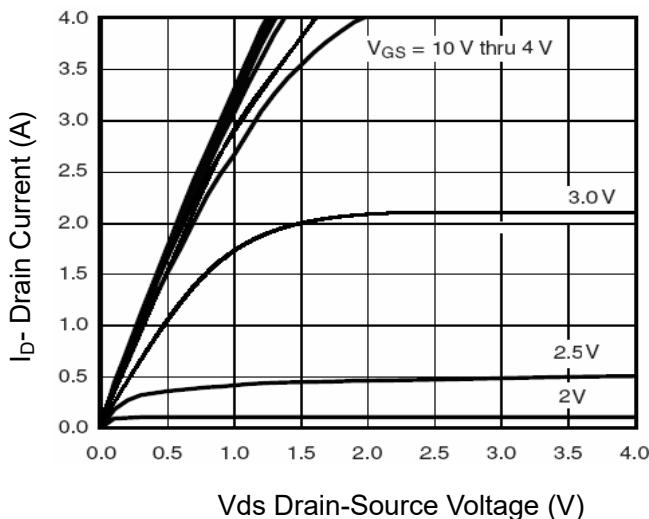


Figure 1 Output Characteristics

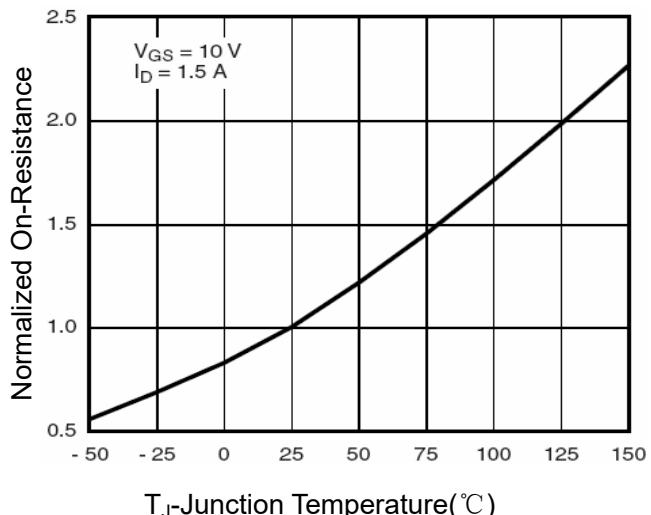


Figure 4 Rdson- Junction Temperature

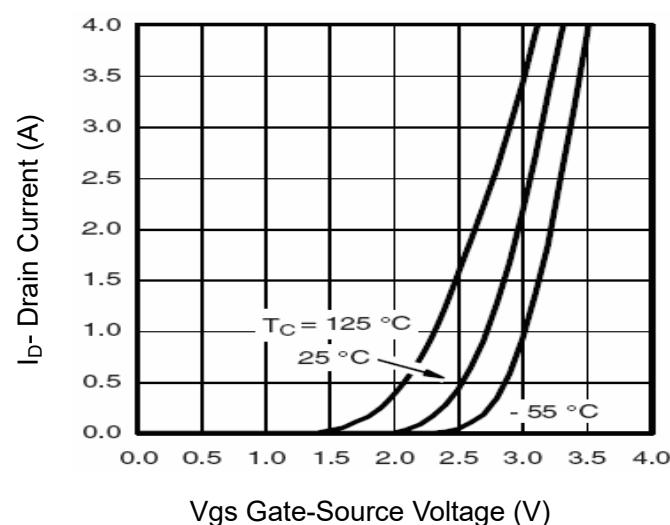


Figure 2 Transfer Characteristics

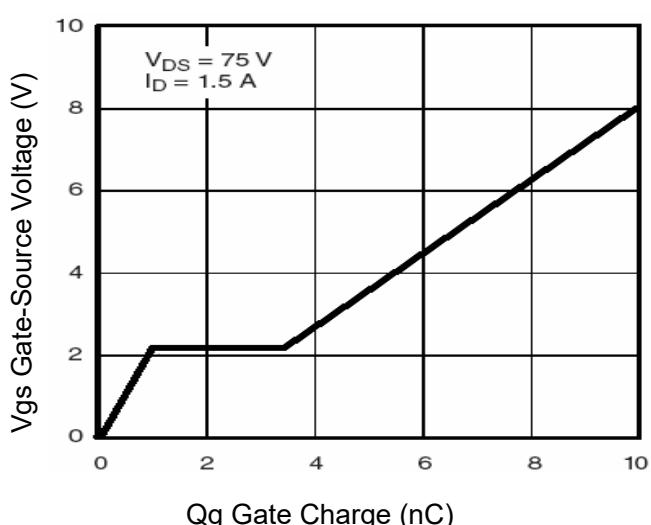


Figure 5 Gate Charge

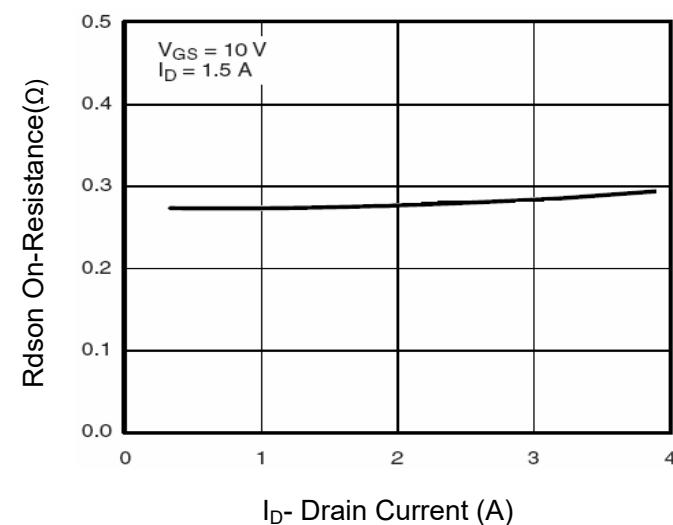


Figure 3 Rdson- Drain Current

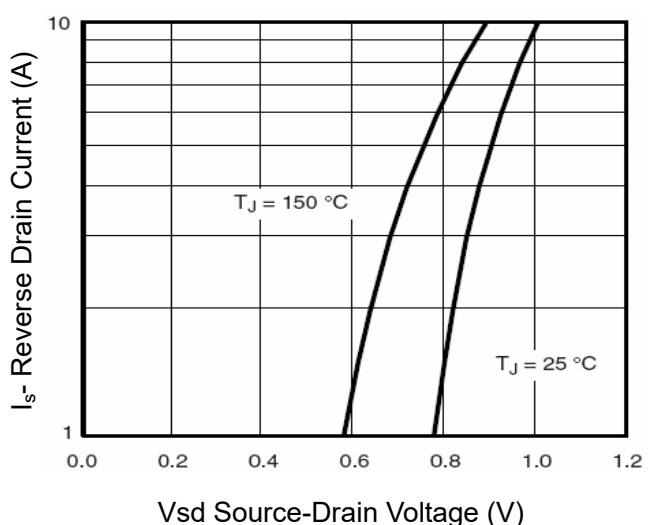


Figure 6 Source- Drain Diode Forward

N-Channel Enhancement Mode MOSFET

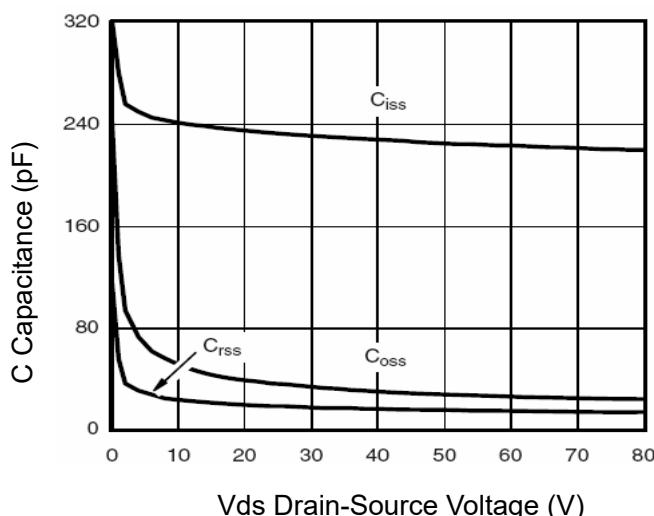


Figure 7 Capacitance vs Vds

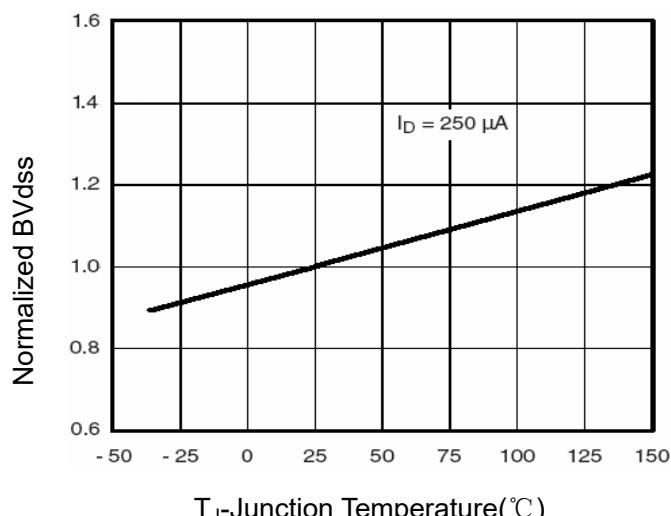


Figure 9 BV_{DSS} vs Junction Temperature

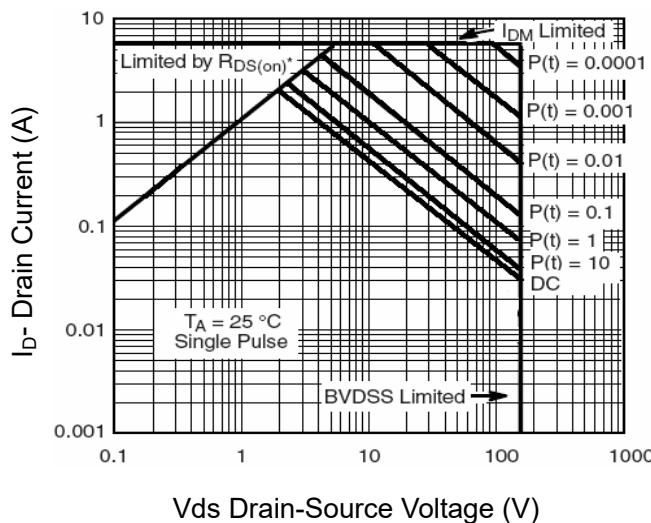


Figure 8 Safe Operation Area

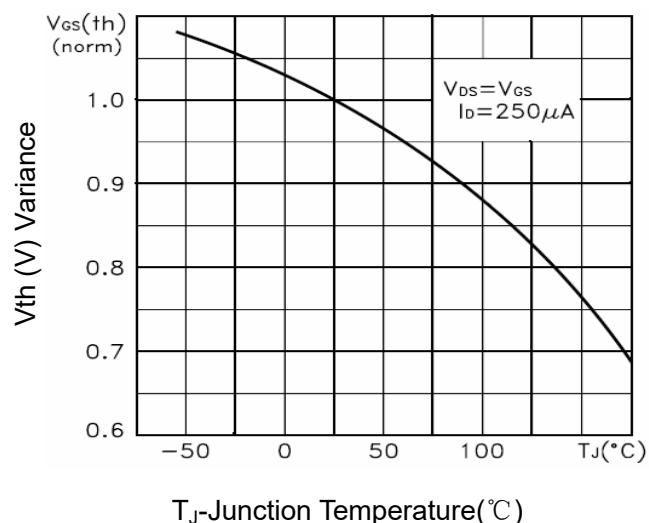


Figure 10 $V_{GS(th)}$ vs Junction Temperature

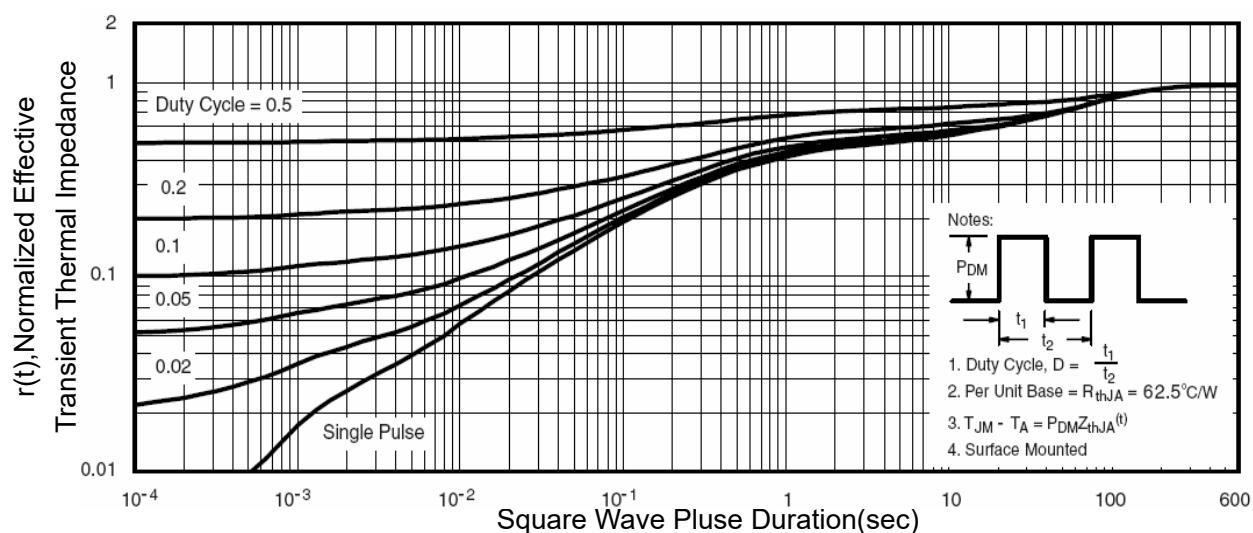
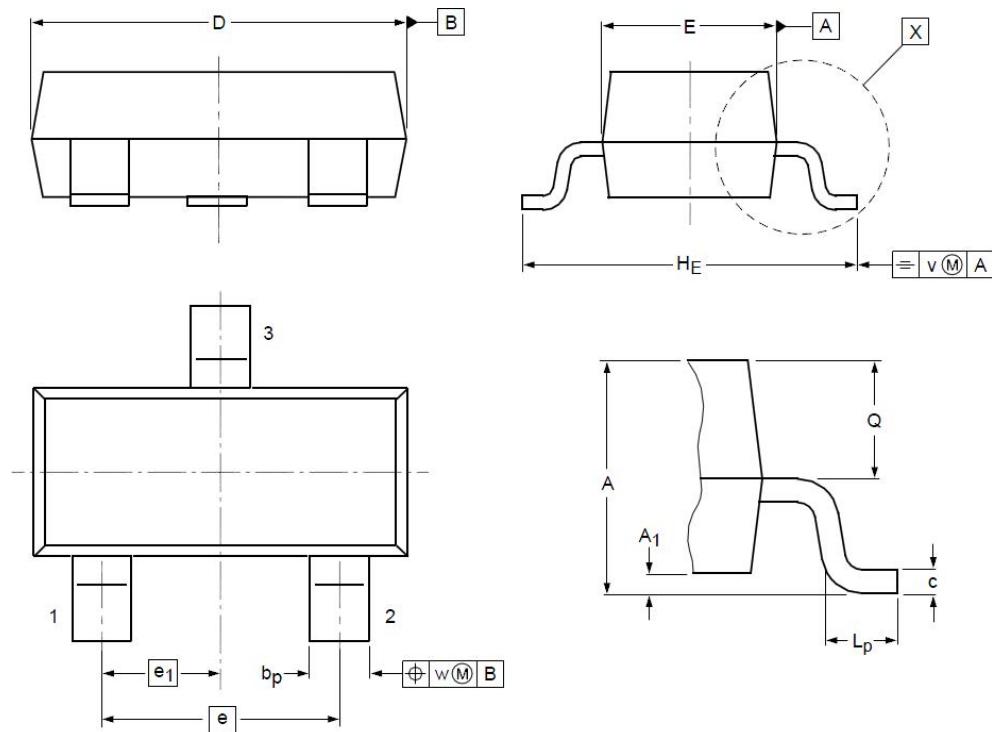


Figure 11 Normalized Maximum Transient Thermal Impedance

N-Channel Enhancement Mode MOSFET
SOT23-3L Package Outline Dimensions


Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.90	1.07	1.25	e ₁	--	0.95	--
A ₁	0.01	0.05	0.10	H _E	2.50	2.80	3.00
b _p	0.30	0.40	0.50	L _P	0.30	0.45	0.60
c	0.10	0.15	0.20	Q	0.23	0.28	0.33
D	2.70	2.90	3.10	V	--	0.20	--
E	1.40	1.55	1.75	W	--	0.20	--
e	--	1.90	--				